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Application Number		10551745					
Filing Date		2007-03-19					
First Named Inventor	Edmu	Edmund Riedl					
Art Unit							
Examiner Name							
Attorney Docket Number		I431 131 101/FIN421PCT/US					

Examiner Initial*	Cite No	Patent Number	Kind Code <sup>1</sup>	Issue C	ate	Name of Patentee or Applicant of cited Document			Pages,Columns,Lines where Relevant Passages or Relevar Figures Appear		
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	1	2930779	DE			1980-02-07	Tokyo Shibaura Denki K. K.,				
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	3	2000294444	JP		2000-10-20		nitomo Electric Istries			
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	1	CHIN et al., Advances in bonding technology for electronic packaging, Journal of Electronic Packaging, Vol. 115, June 1993, 1 pp.								
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